

❏ Drafts

❏ Pending

❏ Active

❏ L1: (1390) (semiconductor near (chip die IC)) with polymer

❏ L2: (4) (semiconductor near (chip die IC)) with polymer with (a

❏ L4: (4) 2 and (@ad<"20040924" @rlad<"20040924")

❏ L5: (59) (semiconductor near (chip die IC)) and (polymer with (

❏ L6: (59) 5 and (@ad<"20040924" @rlad<"20040924")

❏ L10: (4) polymer with (encapsulant\$3) near3 (active near surfac

❏ L11: (4) 10 and (@ad<"20040924" @rlad<"20040924")

❏ L12: (17) polymer with (encapsulant\$3) near3 (bond near wir\$3)

❏ L13: (17) 12 and (@ad<"20040924" @rlad<"20040924")

❏ L14: (0) 257/666.ccls. and (polymer with (encapsulant\$3) near3

❏ Failed

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Search: Browse:

DB: US-PG-PUB:USPAT:USOCR:EPO:JPO:DERWENT:IBM_T08

Default operator: OR

12 and (@ad<"20040924" @rlad<"20040924")

☐ Purge

☐ Highlight all hit terms initially

BRS form

ISAR form

Image

Text

HTML

	U	Document ID	Issued Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	B	
1	<input checked="" type="checkbox"/>	US 6392291 B1	20020521	18	Semiconductor component having selected terminal	257/678	257/698; 257/734;		Corisis; David J.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input checked="" type="checkbox"/>	US 6391681 B1	20020521	17	Semiconductor component having selected terminal	438/106	257/E21.508; 257/E23.07		Corisis; David J.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input checked="" type="checkbox"/>	US 6537850 B1	20030325	17	Method for fabricating semiconductor components	438/106	257/E21.508; 257/E23.07;		Corisis; David J.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	US 20030207501 A1	20031106	16	Semiconductor component with adjustment circuitry and	438/128	257/E23.171; 438/131;		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	US 20040009631 A1	20040115	16	Semiconductor package with circuit side polymer layer	438/127	257/E21.508; 257/E23.039;		Connell, Mike et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input checked="" type="checkbox"/>	US 6753482 B1	20040622	14	Semiconductor component with adjustment circuitry	174/261	174/255; 257/E23.171		Schoenfeld; Aaron M. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	US 20040135253 A1	20040715	16	Semiconductor component with electrical characteristic	257/738	257/E23.171		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	US 20040171191 A1	20040902	16	Stacked semiconductor package with circuit side	438/112	257/782; 257/784;		Connell, Mike et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input checked="" type="checkbox"/>	US 6791168 B1	20040914	14	Semiconductor package with circuit side polymer layer	257/668	257/737; 257/784;		Connell; Mike et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	<input type="checkbox"/>	US 20040201111 A1	20041014	11	Interposer substrates with multisegment interconnect	257/782	257/780; 257/783;		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
11	<input type="checkbox"/>	US 20040201075 A1	20041014	9	Semiconductor die configured for use with interposer	257/459	257/E23.004		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
12	<input type="checkbox"/>	US 20040200063 A1	20041014	10	Interposer substrates with multi-segment interconnect	29/830	257/E23.004; 29/846;		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
13	<input type="checkbox"/>	US 6014226 B1	20050705	15	Semiconductor component with	257/209	257/200		Thurgood, Blaine J.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

THN